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PATENT  
REPLY FILED UNDER EXPEDITED  
PROCEDURE PURSUANT TO  
37 CFR § 1.116

**Amendments to the Specification:**

Please replace the paragraph beginning on page 2, line 9 and ending on page 2, line 14, with the following rewritten paragraph:

-- To overcome such a problem, a technique filling up microvia holes with electrolytic plating is proposed. For example, Japanese Laid-open Patent Publication Heisei 11, No. 8469 discloses the technique of filling up microvia holes by performing electric metal plating with PR electrolysis after an electroless metal film is formed. --

Please replace the paragraph beginning on page 3, line 1 and ending on page 3, line 5, with the following rewritten paragraph:

-- Furthermore, to solve the problems occurring when a soluble anode is used, for example, Japanese Laid-open Patent Publication Heisei 8, No. 507106 discloses a metal plating method using an insoluble anode and a plating solution to which an oxidation-reduction compound is added.--